



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMAJ170A-TR	8HST*TWU201D	A	64BA	2017-04-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	70.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.14-2.76-1.94	2	J bend	
Comment	SMA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	die backside metal-leadframe metal	629
Lead	1.38	soft solder	19671

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name		8HST*TWU201D					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	1.601	mg	supplier	die	Silicon (Si)	7440-21-3		1.572	mg	981898	22471	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3122	71	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	3745	86	
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	3745	86	
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1248	29	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6242	143	
Leadframe	Copper & its alloys	29.843	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.776	mg	997755	425361	
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.030	mg	1005	429	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.034	mg	1139	486	
				supplier	metallization	Phosphorus (P)	12185-10-3		0.003	mg	101	43	
Soft solder	Solder	1.497	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	1.377	mg	919840	19671	
				supplier	solder	Silver (Ag)	7440-22-4		0.037	mg	24716	529	
				supplier	solder	Tin (Sn)	7440-31-5		0.075	mg	50100	1071	
				supplier	solder	flux residue	Proprietary		0.008	mg	5344	110	
Encapsulation	Other Organic Materials	24.837	mg	supplier	mold compound	Amorphous Silica	7631-86-9		18.155	mg	730966	259357	
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.719	mg	189999	67414	
				supplier	mold compound	Phenol resin	9003-35-4		0.745	mg	29996	10643	
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		0.745	mg	29996	10643	
				supplier	mold compound	Carbon black	1333-86-4		0.224	mg	9017	3200	
				supplier	mold compound	Triphenylphophine	603-35-0		0.174	mg	7006	2486	
Connections coating	Solder	0.741	mg	supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.075	mg	3020	1071	
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	10586	
Clip	Copper & its alloys	11.481	mg	supplier	alloy	Copper (Cu)	7440-50-8		11.481	mg	1000000	164014	